

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Yong Liu</td> <td>03/26/2008</td> </tr> <tr> <td>Jeff Ju</td> <td>03/20/2008</td> </tr> <tr> <td>Zhongfa Yuan</td> <td>03/20/2008</td> </tr> <tr> <td>Yongjin (Roger) Luo</td> <td>03/20/2008</td> </tr> </tbody> </table>		Name	Execution Date	Yong Liu	03/26/2008	Jeff Ju	03/20/2008	Zhongfa Yuan	03/20/2008	Yongjin (Roger) Luo	03/20/2008		
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<table border="1"> <tr> <td>Name:</td> <td>FAIRCHILD SEMICONDUCTOR CORPORATION</td> </tr> <tr> <td>Street Address:</td> <td>82 Running Hill Road</td> </tr> <tr> <td>Internal Address:</td> <td>MS: 35-4E</td> </tr> <tr> <td>City:</td> <td>South Portland</td> </tr> <tr> <td>State/Country:</td> <td>MAINE</td> </tr> <tr> <td>Postal Code:</td> <td>04106</td> </tr> </table>		Name:	FAIRCHILD SEMICONDUCTOR CORPORATION	Street Address:	82 Running Hill Road	Internal Address:	MS: 35-4E	City:	South Portland	State/Country:	MAINE	Postal Code:	04106
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CORRESPONDENCE DATA													
<p>Fax Number: 5852954401 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: (585) 295-4469 Email: RochesterIP@hblaw.com Correspondent Name: THOMAS R FITZGERALD Address Line 1: HISCOCK & BARCLAY, LLP Address Line 2: 2000 HSBC PLZ., 100 CHESTNUT ST. Address Line 4: ROCHESTER, NEW YORK 14604</p>													
ATTORNEY DOCKET NUMBER:	3059176												
NAME OF SUBMITTER:	Thomas R. FitzGerald												

CH \$40.00 7768108

Total Attachments: 6

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ASSIGNMENT OF PATENT APPLICATION

JOINT

WHEREAS, Yong Liu of 30 Longmeadow Road, Scarborough, ME 04074; Jeff Ju of 81 Quincy Drive, Gorham, ME 04038; Zhongfa Yuan of 1, Sutong Road, China-Singapore Suzhou Industrial Park, Suzhou, Jiangsu, 215021 People's Republic of China; and Roger Luo of 822 Yishan Road, Shanghai, 200030 People's Republic of China, hereinafter referred to as "Assignors," are the inventors of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention: SEMICONDUCTOR DIE PACKAGE INCLUDING
EMBEDDED FLIP CHIP

Date(s) of execution of Declaration:

Filing Date:

Application No.: ; and

WHEREAS, Fairchild Semiconductor Corporation, a corporation of the state of Delaware, located at 82 Running Hill Road, MS 35-4E, South Portland, ME 04106, hereinafter referred to as "ASSIGNEE," is desirous of acquiring an interest in the invention and application and in any U.S. Letters Patent and Registrations which may be granted on the same;

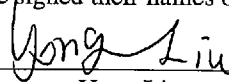
For good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have assigned, and by these presents do assign to Assignee all right, title and interest in and to the invention and application and to all foreign counterparts (including patent, utility model and industrial designs), and in and to any Letters Patent and Registrations which may hereafter be granted on the same in the United States and all countries throughout the world, and to claim the priority from the application as provided by the Paris Convention. The right, title and interest is to be held and enjoyed by Assignee and Assignee's successors and assigns as fully and exclusively as it would have been held and enjoyed by Assignors had this Assignment not been made, for the full term of any Letters Patent and Registrations which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignors further agree that they will, without charge to Assignee, but at Assignee's expense, (a) cooperate with Assignee in the prosecution of U.S. Patent applications and foreign counterparts on the invention and any improvements, (b) execute, verify, acknowledge and deliver all such further papers, including patent applications and instruments of transfer, and (c) perform such other acts as Assignee lawfully may request to obtain or maintain Letters Patent and Registrations for the invention and improvements in any and all countries, and to vest title thereto in Assignee, or Assignee's successors and assigns.

Assignors hereby authorize and request Townsend and Townsend and Crew LLP, Two Embarcadero Center, Eighth Floor, San Francisco, CA 94111-3834, to insert herein above the application number and filing date of said application when known.

IN TESTIMONY WHEREOF, Assignors have signed their names on the dates indicated.

Dated: 03/26/2008

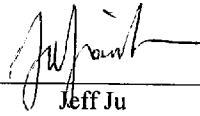

Yong Liu

Assignment

Attorney Docket No.: 018865-028000US

Page 2

Dated: 03/20/08



Jeff Ju

Dated: _____

Zhongfa Yuan

Dated: _____

Roger Luo

61301301 v1

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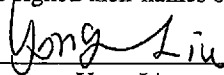
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